Global and China Advanced Packaging Industry Report, 2019-2025

May 2019

ResearchInChina
www.researchinchina.com

STUDY GOAL AND OBJECTIVES

This report provides the industry executives with strategically significant competitor information, analysis, insight and projection on the competitive pattern and key companies in the industry, crucial to the development and implementation of effective business, marketing and R&D programs.

REPORT OBJECTIVES

- To establish a comprehensive, factual, annually updated and cost-effective information base on market size, competition patterns, market segments, goals and strategies of the leading players in the market, reviews and forecasts.
- To assist potential market entrants in evaluating prospective acquisition and joint venture candidates.
- To complement the organizations' internal competitor information gathering efforts with strategic analysis, data interpretation and insight.
- To suggest for concerned investors in line with the current development of this industry as well as the development tendency.
- To help company to succeed in a competitive market, and

METHODOLOGY

Both primary and secondary research methodologies were used in preparing this study. Initially, a comprehensive and exhaustive search of the literature on this industry was conducted. These sources included related books and journals, trade literature, marketing literature, other product/promotional literature, annual reports, security analyst reports, and other publications. Subsequently, telephone interviews or email correspondence was conducted with marketing executives etc. Other sources included related magazines, academics, and consulting companies.

INFORMATION SOURCES

The primary information sources include Company Reports, and National Bureau of Statistics of China etc.

Abstract

The global semiconductor packaging and testing market is enlarging with the prevalence of consumer electronics, automotive semiconductors and the Internet of Things (IoT), with its size edging up 2.5% year on year to $54.3 billion in 2018, of which the advanced packaging sales rose by 6.6% to approximately $25.6 billion in 2018, a figure projected to be $42.8 billion in 2025, at a CAGR of 7.6% or so between 2018 and 2025. To better meet the domestic and foreign demand for advanced packaging technology, Chinese packaging and testing companies have quickened their pace of deployments in 3D, SIP and WLCSP where they put more in research and development, which thus sends the market size of mid- and high-end packaging to $5.88 billion, or 30% of the total.

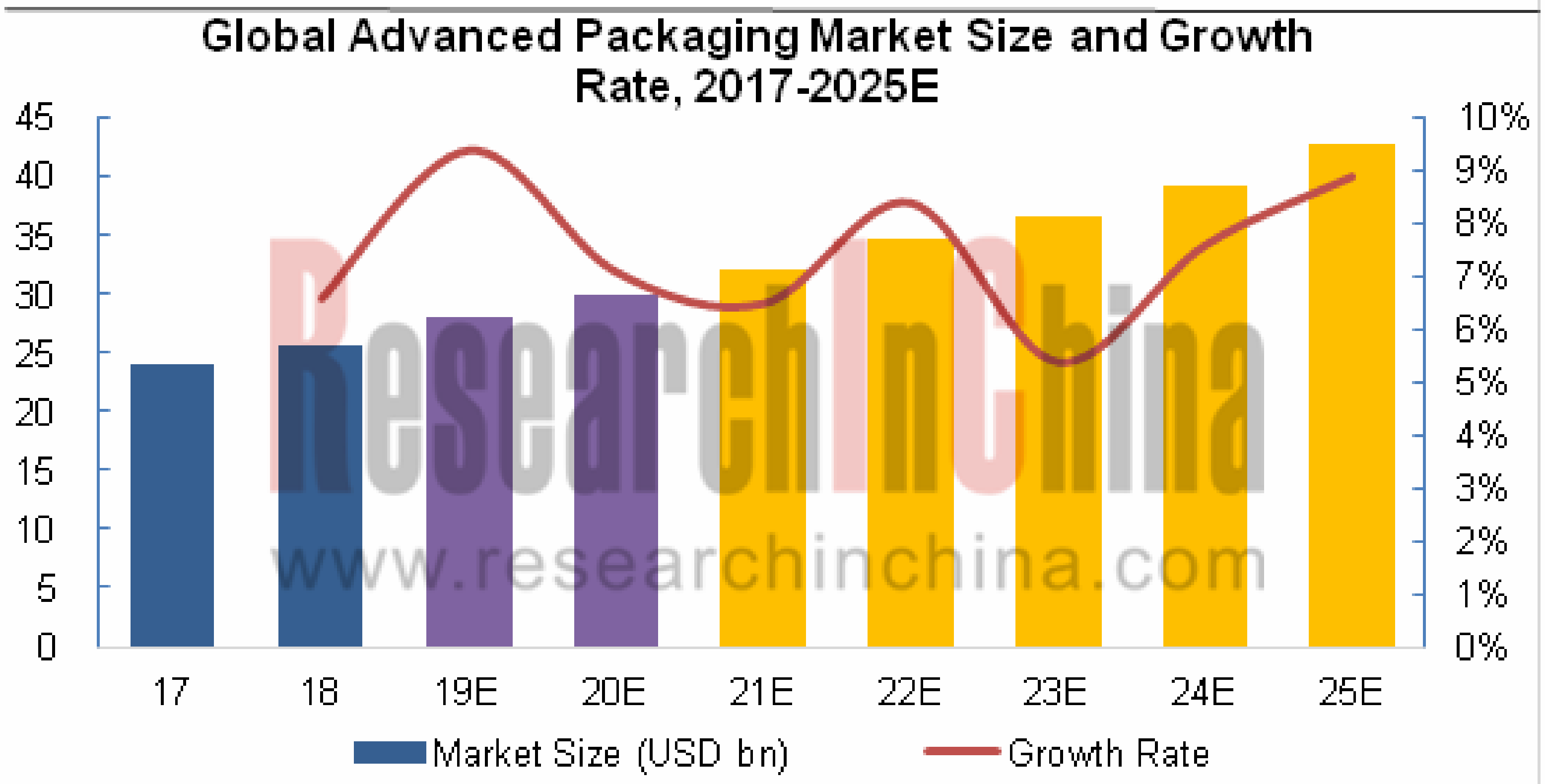
Foreign companies led by ASMPacific Technology (ASMP), US-based Alltech, Germany's TPT and Austrian vendor FK, are the main suppliers of wire bonder, a key device for semiconductor packaging, among which ASMP boasts the biggest share, or 25% of the global market in the back-end-of-line (BEOL) process. America's Teradyne and Japan-based Advantest are the two major vendors of sorter and tester, two kinds of semiconductor testing equipment, commanding 48% and 39% of the global market, separately.

The packaging and testing market in Mainland China has been ballooning to the second largest around the globe, as local players independently develop advanced packaging technology and acquire foreign firms, for example, Jiangsu Changjiang Electronics Technology Co., Ltd. (JCET) acquired STATS ChipPAC based in Singapore, making itself the world's third-ranking packaging and testing plant only second to ASE Group and Amkor; Tianshui Huatian Technology Co., Ltd. acquired Flip Chip International, LLC (FCI), an American company; Tongfu Microelectronics Co., Ltd. has also been on the global top ten packaging and testing plants list after acquiring AMD's packaging and testing subsidiary. All of which is a proof that global packaging and testing operations are gathering around Mainland China.

Global and China Advanced Packaging Industry Report, 2019-2025 highlights the following:

- Global semiconductor industry (development course, market size, competitive pattern, packaging industry at a glance, etc.);
- IC packaging upstream and downstream industries: (wafer, memory, collector, PC, etc.) (market size, output & sales, competitive pattern, etc.);
- Packaging technology trends (SIP, 2.5D, 3D, WLCSP, etc.);
- Advanced packaging industry (market size, competitive pattern, development trend, etc.);
- 15 key foreign and Chinese vendors (ASMP, Kulicke & Soffa, Advantest, etc.) (profile, operation, R&D, manufacturing base distribution, technical characteristics, etc.).

Room 801, B1, Changyuan Tiandi Building, No. 18, Suzhou Street, Haidian District, Beijing, China 100080
Phone: +86 10 82600828 ● Fax: +86 10 82601570 ● www.researchinchina.com ● report@researchinchina.com



Source: Global and China Advanced Packaging Industry Report, 2019-2025 May 2019

Table of contents

Table of contents

Table of contents

Table of contents

Table of contents

Table of contents

ResearchInChina
The Vertical Portal for China Business Intelligence

How to Buy

You can place your order in the following alternative ways:

1.Order online at www.researchinchina.com

2.Fax order sheet to us at fax number:+86 10 82601570

3. Email your order to: report@researchinchina.com

4. Phone us at +86 10 82600828

Party A:			
Name:			
Address:			
Contact Person:		Tel	
E-mail:		Fax	

Party B:			
Name:	Beijing Waterwood Technologies Co., Ltd (ResearchInChina)		
Address:	Room 801, B1, Changyuan Tiandi Building, No. 18, Suzhou Street, Haidian District, Beijing, China 100080		
Contact Person:	Liao Yan	Phone:	86-10-82600828
E-mail:	report@researchinchina.com	Fax:	86-10-82601570
Bank details:	Beneficial Name: Beijing Waterwood Technologies Co., Ltd Bank Name: Bank of Communications, Beijing Branch Bank Address: NO.1 jinxiyuan shijicheng,Landianchang,Haidian District,Beijing Bank Account No #: 110060668012015061217 Routing No # : 332906 Bank SWIFT Code: COMMCNSHBJG		

Title	**Format**	**Cost**
Total		

Choose type of format

PDF (Single user license) …………..3,000 USD

Hard copy ………………….……. 3,200 USD

PDF (Enterprisewide license)…....... 4,500 USD

※ Reports will be dispatched immediately once full payment has been received. Payment may be made by wire transfer or credit card via PayPal.

ResearchInChina
www.researchinchina.com

RICDB service

About ResearchInChina

ResearchInChina (www.researchinchina.com) is a leading independent provider of China business intelligence. Our research is designed to meet the diverse planning and information needs of businesses, institutions, and professional investors worldwide. Our services are used in a variety of ways, including strategic planning, product and sales forecasting, risk and sensitivity management, and as investment research.

Our Major Activities

- ***Multi-users market reports***
- ***Database-RICDB***
- ***Custom Research***
- ***Company Search***

RICDB (http://www.researchinchina.com/data/database.html), is a visible financial data base presented by map and graph covering global and China macroeconomic data, industry data, and company data. It has included nearly 500,000 indices (based on time series), and is continuing to update and increase. The most significant feature of this base is that the vast majority of indices (about 400,000) can be displayed in map.

After purchase of our report, you will be automatically granted to enjoy 2 weeks trial service of RICDB for free.

After trial, you can decide to become our formal member or not. We will try our best to meet your demand. For more information, please find at www.researchinchina.com

For any problems, please contact our service team at: